

576103

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	116	ball-michael-b.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2	IS&R	L2	12	(("5952725") or ("6165815") or ("6140149") or ("6407456") or ("6337227") or ("6071754") or ("6165815")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	BRS	L3	0	438/108,617,123.ccls. and (chip die IC) and (bump ball) and (conductive adj epoxy adj adhesiv\$4) with cur\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	BRS	L4	0	438/108.ccls. and (chip die IC) and (bump ball) and (conductive adj epoxy adj adhesiv\$4) with cur\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
5	BRS	L5	0	438/108.ccls. and (chip die IC) and (bump ball) and (conductive adj epoxy adj adhesiv\$4) with curing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
6	BRS	L6	0	438/108,617,123.ccls. and (chip die IC) and (bump ball) and (conductive adj epoxy adj adhesiv\$4) with (cure curing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	L7	0	257/777-778,784,723.ccls. and (chip die IC) and (bump ball) and (conductive adj epoxy adj adhesiv\$4) with (cure curing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
8	BRS	L8	0	257/777-778,784,723.ccls. and (conductive adj epoxy adj adhesiv\$4) with (cure curing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
9	BRS	L9	14	(conductive adj epoxy adj adhesiv\$4) with (cure curing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
10	BRS	L10	1	257/777-778,784,723.ccls. and (conductive adj epoxy adj adhesiv\$4) and (ball bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
11	BRS	L11	3	257/676,684,685-686.ccls. and (conductive adj epoxy adj adhesiv\$4) and (ball bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

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